

1A Avg.

30 Volts

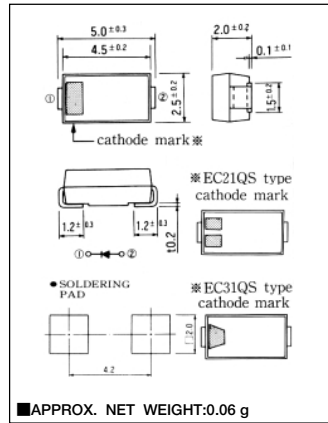
SBD

EC10QS03L

■最大定格 Maximum Ratings

Item	Symbol	Conditions	Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	V_{RRM}	30	V
平均整流電流 Average Rectified Forward Current	I_O	50Hz, 正弦半波通電抵抗負荷 50Hz Half Sine Wave Resistive Load	$T_a=28^\circ\text{C}^{*1}$ 1.0 A
			$T_a=58^\circ\text{C}^{*2}$ 1.0 A
実効順電流 R.M.S. Forward Current	$I_{F(RMS)}$	1.57	A
サージ順電流 Surge Forward Current	I_{FSM}	20 50Hz正弦半波, 1サイクル, 非くり返し 50Hz Half Sine Wave, 1cycle, Non-repetitive	A
動作接合温度範囲 Operating Junction Temperature Range	T_{jw}	-40~+150	°C
保存温度範囲 Storage Temperature Range	T_{stg}	-40~+150	°C

■OUTLINE DRAWING(mm)



■APPROX. NET WEIGHT:0.06 g

■電氣的・熱的特性 Electrical/Thermal Characteristics

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit	
ピーク逆電流 Peak Reverse Current	I_{RM}	$T_j=25^\circ\text{C}, V_{RM}=V_{RRM}$	—	—	1	mA	
ピーク順電圧 Peak Forward Voltage	V_{FM}	$T_j=25^\circ\text{C}, I_{FM}=1\text{A}$	—	—	0.45	V	
熱抵抗 Thermal Resistance	$R_{th(j-a)}$	接合部・周囲間 Junction to Ambient	Glass Epoxy Substrate Mounted ^{*1}		—	157	°C/W
			Alumina Substrate Mounted ^{*2}		—	108	°C/W

*1: プリント基板実装/Glass-Epoxy Substrate mounted (Soldering Lands= 2 × 2 mm, Both Sides)
*2: アルミナ基板実装/Alumina Substrate mounted (Soldering Lands= 2 × 2 mm, Both Sides)

■定格・特性曲線

